

# Specification of Thermoelectric Module

## TEC4-127-71-31-17-03T

### Description

The TEC4-127-71-31-17-03 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 127-71-31-17 couples module in size of 15mm×15mm (top)/40mm ×40mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

### Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

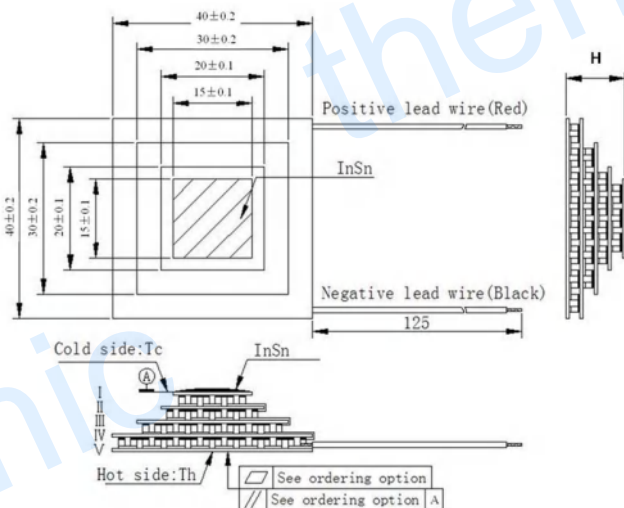
### Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

### Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	112	126	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	14.6	16.4	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (Amps)	3.4	3.4	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	7.4	8.1	Cooling capacity at cold side of the module under DT= 0 °C
AC resistance (Ohms)	4.2	4.7	The module resistance is tested under AC
Tolerance	10%		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

#### A. Solder:

1. T100: BiSn (T<sub>melt</sub>=138°C)
2. T200: CuAgSn (T<sub>melt</sub> = 217°C)
3. T240: SbSn (T<sub>melt</sub> = 240°C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

### Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 13.3±0.4	0: 0.08/0.08	125±1/Specify
TF	1: 13.3±0.2	1: 0.03/0.03	125±1/Specify

Ex. TF01: Thickness 13.3±0.4 (mm) and Flatness/ Parallelism (mm): 0.03/0.03(mm)

### Naming for the Module

TEC4-127-71-31-17-03T-X-X-X-X



TEC4-127-71-31-17-03T-T100-NS-TF01-AIO

T100: BiSn (T<sub>melt</sub>=138°C)

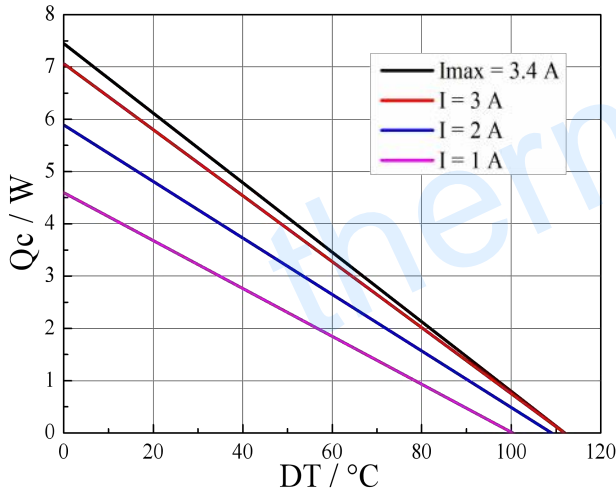
NS: No sealing

AIO: Alumina, white 96%

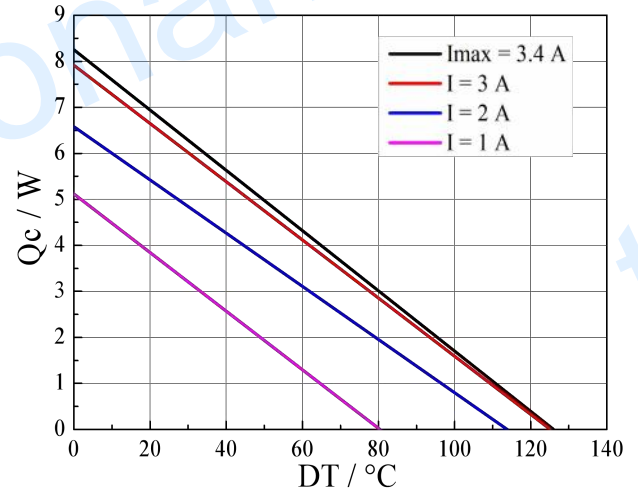
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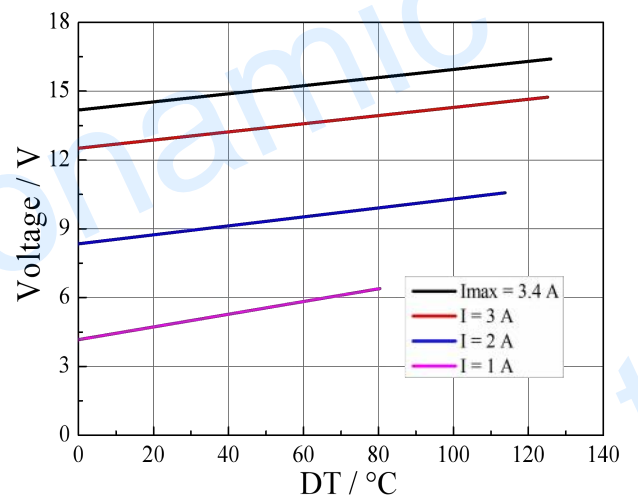
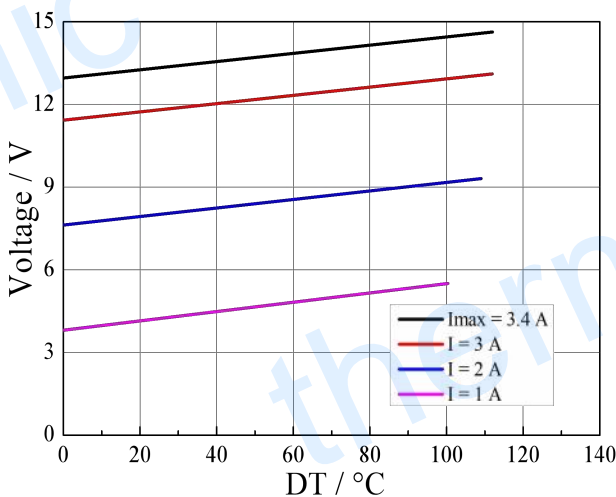
Performance Curves at  $T_h=27^\circ\text{C}$



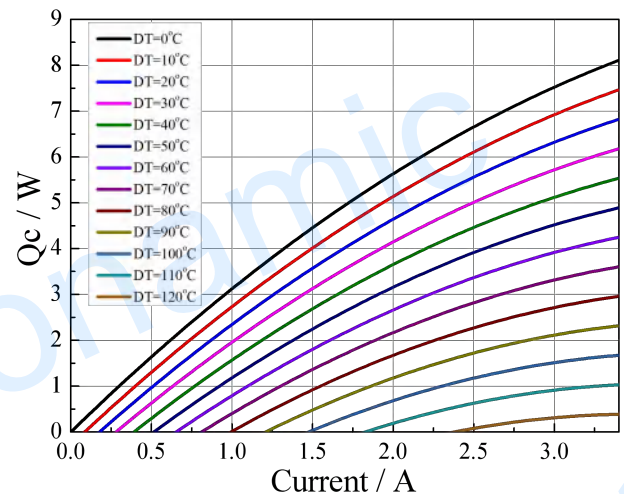
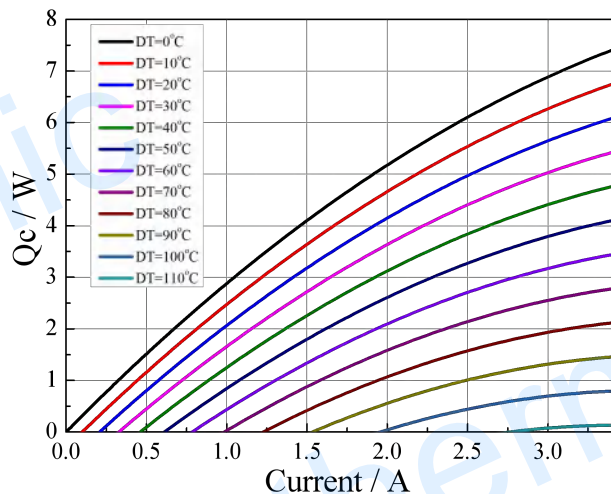
Performance Curves at  $T_h=50^\circ\text{C}$



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

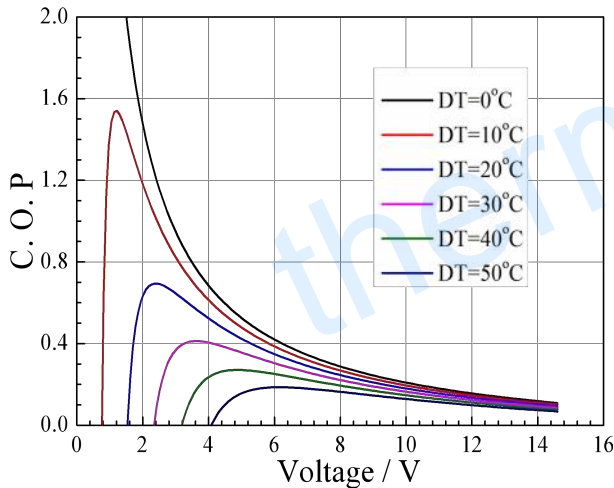


Standard Performance Graph  $Q_c = f(I)$

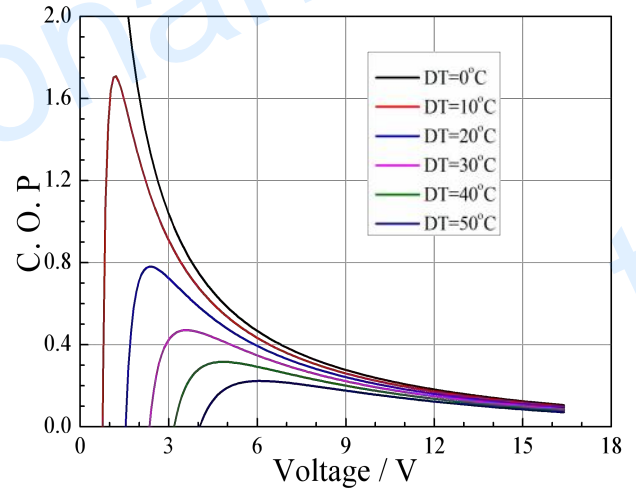
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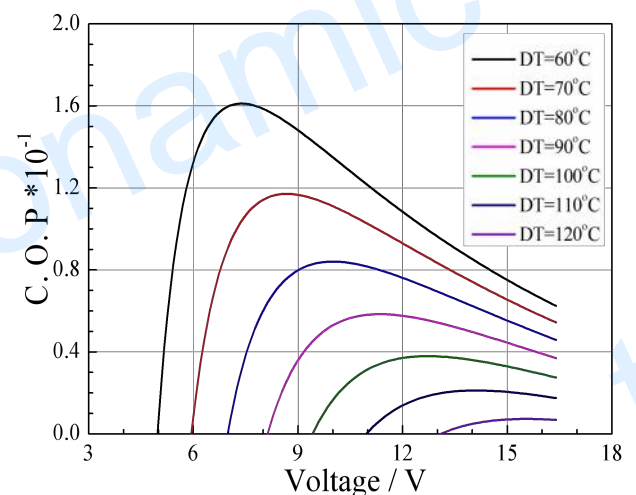
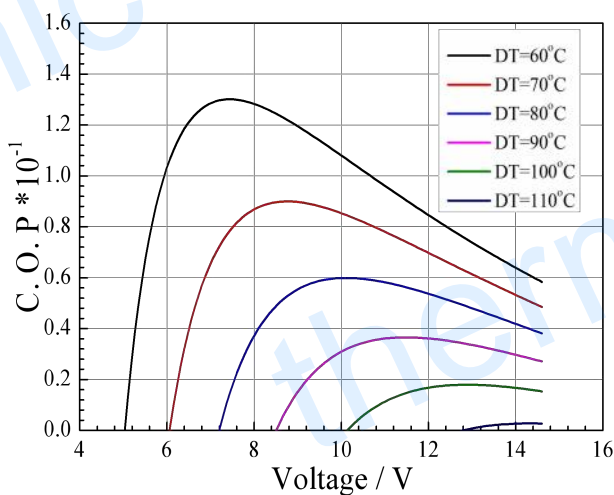
Performance Curves at  $T_h=27^\circ\text{C}$



Performance Curves at  $T_h=50^\circ\text{C}$



Standard Performance Graph  $\text{COP} = f(V)$  of DT ranged from 0 to  $50^\circ\text{C}$



Standard Performance Graph  $\text{COP} = f(V)$  of DT ranged from 60 to 110/120  $^\circ\text{C}$

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below  $100^\circ\text{C}$
- Operation below  $I_{\text{max}}$  or  $V_{\text{max}}$
- Work under DC

**Note:** All specifications subject to change without notice.